

Johan Liu

List of Publications by Year in descending order

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163
papers

3,966
citations

109321

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55
g-index

166
all docs

166
docs citations

166
times ranked

4724
citing authors

| # | ARTICLE | IF | CITATIONS |
|----|--|-----|-----------|
| 1 | Improved Thermal Properties of Three-Dimensional Graphene Network Filled Polymer Composites. Journal of Electronic Materials, 2022, 51, 420-425. | 2.2 | 6 |
| 2 | Transparent heaters based on CVD grown few-layer graphene. Journal of Materials Science: Materials in Electronics, 2022, 33, 3586-3594. | 2.2 | 0 |
| 3 | Graphene Oxide and Nitrogen-Doped Graphene Coated Copper Nanoparticles in Water-Based Nanofluids for Thermal Management in Electronics. Journal of Nanofluids, 2022, 11, 125-134. | 2.7 | 2 |
| 4 | A lightweight and high thermal performance graphene heat pipe. Nano Select, 2021, 2, 364-372. | 3.7 | 12 |
| 5 | A Novel Graphene Quantum Dot-Based mRNA Delivery Platform. ChemistryOpen, 2021, 10, 666-671. | 1.9 | 23 |
| 6 | Degradation of Carbon Nanotube Array Thermal Interface Materials through Thermal Aging: Effects of Bonding, Array Height, and Catalyst Oxidation. ACS Applied Materials & Interfaces, 2021, 13, 30992-31000. | 8.0 | 15 |
| 7 | Graphene-Based Films: Fabrication, Interfacial Modification, and Applications. Nanomaterials, 2021, 11, 2539. | 4.1 | 11 |
| 8 | Exploring Graphene Coated Copper Nanoparticles as a multifunctional Nanofiller for Micro-Scaled Copper Paste. , 2021, , . | | 0 |
| 9 | Thermal Analysis of An Au/Pt/Ti-Based Microheater. , 2021, , . | | 0 |
| 10 | Synergistic Toughening of Graphene Films by Addition of Hydroxylated Carbon Nanotube. , 2021, , . | | 0 |
| 11 | Fabrication and Characterization of Graphene/polyimide Composite Film. , 2021, , . | | 0 |
| 12 | A Critical Assessment of Nano Enhanced Vapor Chamber Wick Structures for Electronics Cooling. , 2021, , . | | 2 |
| 13 | Highly Thermally Conductive Substrate Based on Graphene Film. , 2021, , . | | 0 |
| 14 | Thermal Properties of Laser-induced Graphene Films Photothermally Scribed on Bare Polyimide Substrates. , 2021, , . | | 0 |
| 15 | Thermal Properties of Laser Reduced Graphene Oxide Films. , 2021, , . | | 0 |
| 16 | Aerosol Jet Printing of Graphene and Carbon Nanotube Patterns on Realistically Rugged Substrates. ACS Omega, 2021, 6, 34301-34313. | 3.5 | 11 |
| 17 | Graphene related materials for thermal management. 2D Materials, 2020, 7, 012001. | 4.4 | 161 |
| 18 | Enhanced electrochemical performance of three-dimensional graphene/carbon nanotube composite for supercapacitor application. Journal of Alloys and Compounds, 2020, 820, 153114. | 5.5 | 47 |

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|----|--|------|-----------|
| 19 | Improved Interfacial Bonding Strength and Reliability of Functionalized Graphene Oxide for Cement Reinforcement Applications. Chemistry - A European Journal, 2020, 26, 6561-6568. | 3.3 | 12 |
| 20 | Properties of Undoped Few-Layer Graphene-Based Transparent Heaters. Materials, 2020, 13, 104. | 2.9 | 16 |
| 21 | Synthesis of graphene quantum dots and their applications in drug delivery. Journal of Nanobiotechnology, 2020, 18, 142. | 9.1 | 142 |
| 22 | Analysis of heat dissipation characteristics of three-dimensional graphene-carbon nanotube composite structures. , 2020, , . | | 1 |
| 23 | Thermally Conductive Graphene Film/Indium/Aluminum Laminated Composite by Vacuum Assisted Hot-pressing. , 2020, , . | | 0 |
| 24 | Multiple growth of graphene from a pre-dissolved carbon source. Nanotechnology, 2020, 31, 345601. | 2.6 | 5 |
| 25 | Effects of high temperature treatment of carbon nanotube arrays on graphite: increased crystallinity, anchoring and inter-tube bonding. Nanotechnology, 2020, 31, 455708. | 2.6 | 15 |
| 26 | Scalable production of thick graphene film for next generation thermal management application. Carbon, 2020, 167, 270-277. | 10.3 | 39 |
| 27 | Bipolar electrochemical capacitors using double-sided carbon nanotubes on graphite electrodes. Journal of Power Sources, 2020, 451, 227765. | 7.8 | 8 |
| 28 | Thermally Reduced Graphene Oxide/Carbon Nanotube Composite Films for Thermal Packaging Applications. Materials, 2020, 13, 317. | 2.9 | 19 |
| 29 | Highly Oriented Graphite Aerogel Fabricated by Confined Liquid-Phase Expansion for Anisotropically Thermally Conductive Epoxy Composites. ACS Applied Materials & Interfaces, 2020, 12, 27476-27484. | 8.0 | 32 |
| 30 | High porosity and light weight graphene foam heat sink and phase change material container for thermal management. Nanotechnology, 2020, 31, 424003. | 2.6 | 17 |
| 31 | Graphene based thermal management system for battery cooling in electric vehicles. , 2020, , . | | 8 |
| 32 | Reliability Investigation of a Carbon Nanotube Array Thermal Interface Material. Energies, 2019, 12, 2080. | 3.1 | 11 |
| 33 | Chemical Vapor Deposition of Vertically Aligned Carbon Nanotube Arrays: Critical Effects of Oxide Buffer Layers. Nanoscale Research Letters, 2019, 14, 106. | 5.7 | 8 |
| 34 | Preparation of graphene/aligned carbon nanotube array composite films for thermal packaging applications. Japanese Journal of Applied Physics, 2019, 58, SHHH01. | 1.5 | 6 |
| 35 | Atomic Layer Deposition of Buffer Layers for the Growth of Vertically Aligned Carbon Nanotube Arrays. Nanoscale Research Letters, 2019, 14, 119. | 5.7 | 4 |
| 36 | Highly Thermal Conductive and Electrically Insulated Graphene Based Thermal Interface Material with Long-Term Reliability. , 2019, , . | | 5 |

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| 37 | Mechanical behaviour of sintered silver nanoparticles reinforced by SiC microparticles. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2019, 744, 406-414. | 5.6 | 43 |
| 38 | Manufacturing Graphene-Encapsulated Copper Particles by Chemical Vapor Deposition in a Cold Wall Reactor. <i>ChemistryOpen</i> , 2019, 8, 58-63. | 1.9 | 8 |
| 39 | Effect of Fiber Concentration on Mechanical and Thermal Properties of a Solder Matrix Fiber Composite Thermal Interface Material. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2019, 9, 1045-1053. | 2.5 | 0 |
| 40 | Thermal Interface Materials Based on Vertically Aligned Carbon Nanotube Arrays: A Review. <i>Micro and Nanosystems</i> , 2019, 11, 3-10. | 0.6 | 9 |
| 41 | Thermal conductivity enhancement of carbon@ carbon nanotube arrays and bonded carbon nanotube network. <i>Materials Research Express</i> , 2019, 6, 085616. | 1.6 | 6 |
| 42 | Surface Modification of Graphene for Use as a Structural Fortifier in Water-Borne Epoxy Coatings. <i>Coatings</i> , 2019, 9, 754. | 2.6 | 13 |
| 43 | Graphene-coated copper nanoparticles for thermal conductivity enhancement in water-based nanofluid. , 2019, , . | | 0 |
| 44 | Experimental Measurements of Thermal Performances of Carbon Nanomaterial with Vertical Structures in Hotspot Heat Dissipation *. , 2019, , . | | 0 |
| 45 | Effect of space environment on the reliability of sintered silver nanoparticles reinforced by SiC particles. , 2019, , . | | 0 |
| 46 | RF Properties of Carbon Nanotube / Copper Composite Through Silicon Via Based CPW Structure for 3D Integrated Circuits. , 2019, , . | | 0 |
| 47 | Effect of Boron Nitride Particle Geometry on the Thermal Conductivity of a Boron Nitride Enhanced Polymer Composite Film. , 2019, , . | | 1 |
| 48 | Compact and low loss electrochemical capacitors using a graphite / carbon nanotube hybrid material for miniaturized systems. <i>Journal of Power Sources</i> , 2019, 412, 374-383. | 7.8 | 32 |
| 49 | Understanding noninvasive charge transfer doping of graphene: a comparative study. <i>Journal of Materials Science: Materials in Electronics</i> , 2018, 29, 5239-5252. | 2.2 | 14 |
| 50 | Novel nanostructured thermal interface materials: a review. <i>International Materials Reviews</i> , 2018, 63, 22-45. | 19.3 | 261 |
| 51 | Elevated thermoelectric figure of merit of n-type amorphous silicon by efficient electrical doping process. <i>Nano Energy</i> , 2018, 44, 89-94. | 16.0 | 16 |
| 52 | Reliability study on high thermally conductive graphene film as heat spreader in electronics cooling applications. , 2018, , . | | 0 |
| 53 | Critical Atomic-level Processing Technologies: Remote Plasma-enhanced Atomic Layer Deposition and Atomic Layer Etching. <i>Micro and Nanosystems</i> , 2018, 10, 76-83. | 0.6 | 1 |
| 54 | Vertically Aligned Graphene-based Thermal Interface Material with High Thermal Conductivity. , 2018, , . | | 5 |

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| 55 | Finite Element Analysis to the Constitutive Behavior of Sintered Silver Nanoparticles Under Nanoindentation. International Journal of Applied Mechanics, 2018, 10, 1850110. | 2.2 | 16 |
| 56 | Estimating the constitutive behaviour of sintered silver nanoparticles by nanoindentation. , 2018, , . | | 2 |
| 57 | Highly Thermally Conductive and Light Weight Copper/Graphene Film Laminated composites for Cooling Applications. , 2018, , . | | 4 |
| 58 | Tailoring the Thermal and Mechanical Properties of Graphene Film by Structural Engineering. Small, 2018, 14, e1801346. | 10.0 | 106 |
| 59 | Egg albumen templated graphene foams for high-performance supercapacitor electrodes and electrochemical sensors. Journal of Materials Chemistry A, 2018, 6, 18267-18275. | 10.3 | 21 |
| 60 | Synthesis of a Graphene Carbon Nanotube Hybrid Film by Joule Self-Heating CVD for Thermal Applications. , 2018, , . | | 3 |
| 61 | Improving Thermal Transport at Carbon Hybrid Interfaces by Covalent Bonds. Advanced Materials Interfaces, 2018, 5, 1800318. | 3.7 | 20 |
| 62 | Surface analysis of iron and steel nanopowder. Surface and Interface Analysis, 2018, 50, 1083-1088. | 1.8 | 7 |
| 63 | Control of Nanoplane Orientation in voBN for High Thermal Anisotropy in a Dielectric Thin Film: A New Solution for Thermal Hotspot Mitigation in Electronics. ACS Applied Materials & Interfaces, 2017, 9, 7456-7464. | 8.0 | 9 |
| 64 | Chemical vapor deposition grown graphene on Cu-Pt alloys. Materials Letters, 2017, 193, 255-258. | 2.6 | 13 |
| 65 | Thermal Conductivity Enhancement of Coaxial Carbon@Boron Nitride Nanotube Arrays. ACS Applied Materials & Interfaces, 2017, 9, 14555-14560. | 8.0 | 35 |
| 66 | Stretchable Thermoelectric Generators Metallized with Liquid Alloy. ACS Applied Materials & Interfaces, 2017, 9, 15791-15797. | 8.0 | 72 |
| 67 | Interface and interconnection stresses in electronic assemblies – A critical review of analytical solutions. Microelectronics Reliability, 2017, 79, 206-220. | 1.7 | 17 |
| 68 | Cellulose-derived carbon nanofibers/graphene composite electrodes for powerful compact supercapacitors. RSC Advances, 2017, 7, 45968-45977. | 3.6 | 76 |
| 69 | Efficient surface modification of carbon nanotubes for fabricating high performance CNT based hybrid nanostructures. Carbon, 2017, 111, 402-410. | 10.3 | 50 |
| 70 | Embedded Fin-Like Metal/CNT Hybrid Structures for Flexible and Transparent Conductors. Small, 2016, 12, 1521-1526. | 10.0 | 15 |
| 71 | Two-dimensional hexagonal boron nitride as lateral heat spreader in electrically insulating packaging. Journal Physics D: Applied Physics, 2016, 49, 265501. | 2.8 | 33 |
| 72 | Controllable and fast synthesis of bilayer graphene by chemical vapor deposition on copper foil using a cold wall reactor. Chemical Engineering Journal, 2016, 304, 106-114. | 12.7 | 13 |

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| 73 | Review of current progress of thermal interface materials for electronics thermal management applications. , 2016, , . | | 32 |
| 74 | Development and characterization of graphene enhanced thermal conductive adhesives. , 2016, , . | | 2 |
| 75 | Graphene oxide based coatings on nitinol for biomedical implant applications: effectively promote mammalian cell growth but kill bacteria. RSC Advances, 2016, 6, 38124-38134. | 3.6 | 44 |
| 76 | Enhanced cold wall CVD reactor growth of horizontally aligned single-walled carbon nanotubes. Electronic Materials Letters, 2016, 12, 329-337. | 2.2 | 5 |
| 77 | Vertically aligned CNT-Cu nano-composite material for stacked through-silicon-via interconnects. Nanotechnology, 2016, 27, 335705. | 2.6 | 43 |
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| 79 | Characterization and simulation of liquid phase exfoliated graphene-based films for heat spreading applications. Carbon, 2016, 106, 195-201. | 10.3 | 28 |
| 80 | Synthesis and applications of two-dimensional hexagonal boron nitride in electronics manufacturing. Electronic Materials Letters, 2016, 12, 1-16. | 2.2 | 67 |
| 81 | Mechanical and thermal characterization of a novel nanocomposite thermal interface material for electronic packaging. Microelectronics Reliability, 2016, 56, 129-135. | 1.7 | 15 |
| 82 | Unusual tensile behaviour of fibre-reinforced indium matrix composite and its in-situ TEM straining observation. Acta Materialia, 2016, 104, 109-118. | 7.9 | 13 |
| 83 | Improved Heat Spreading Performance of Functionalized Graphene in Microelectronic Device Application. Advanced Functional Materials, 2015, 25, 4430-4435. | 14.9 | 117 |
| 84 | Flexible Multifunctionalized Carbon Nanotubes-Based Hybrid Nanowires. Advanced Functional Materials, 2015, 25, 4135-4143. | 14.9 | 20 |
| 85 | A High Performance Ag Alloyed Nano-scale n-type Bi ₂ Te ₃ Based Thermoelectric Material. Materials Today: Proceedings, 2015, 2, 610-619. | 1.8 | 17 |
| 86 | Combination of positive charges and honeycomb pores to promote MC3T3-E1 cell behaviour. RSC Advances, 2015, 5, 42276-42286. | 3.6 | 7 |
| 87 | Measurement of Dielectric Properties of Ultrafine BaTiO ₃ Using an Organic-Inorganic Composite Method. Journal of Electronic Materials, 2015, 44, 2300-2307. | 2.2 | 0 |
| 88 | Tape-Assisted Transfer of Carbon Nanotube Bundles for Through-Silicon-Via Applications. Journal of Electronic Materials, 2015, 44, 2898-2907. | 2.2 | 21 |
| 89 | Vertically Stacked Carbon Nanotube-Based Interconnects for Through Silicon Via Application. IEEE Electron Device Letters, 2015, 36, 499-501. | 3.9 | 44 |
| 90 | Cooling hot spots by hexagonal boron nitride heat spreaders. , 2015, , . | | 7 |

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| 91 | Characterization of nano-enhanced interconnect materials for fine pitch assembly. Soldering and Surface Mount Technology, 2014, 26, 12-17. | 1.5 | 2 |
| 92 | <scp>HB</scp> affects astrocyte morphology, proliferation, differentiation, and the expression of intermediate filament proteins. Journal of Neurochemistry, 2014, 128, 878-889. | 3.9 | 43 |
| 93 | Stem cell responses to plasma surface modified electrospun polyurethane scaffolds. Nanomedicine: Nanotechnology, Biology, and Medicine, 2014, 10, e949-e958. | 3.3 | 50 |
| 94 | A new solder matrix nano polymer composite for thermal management applications. Composites Science and Technology, 2014, 94, 54-61. | 7.8 | 21 |
| 95 | A carbon fiber solder matrix composite for thermal management of microelectronic devices. Journal of Materials Chemistry C, 2014, 2, 7184-7187. | 5.5 | 21 |
| 96 | Novel thermal interface materials: boron nitride nanofiber and indium composites for electronics heat dissipation applications. Journal of Materials Science: Materials in Electronics, 2014, 25, 2333-2338. | 2.2 | 26 |
| 97 | Thermal chemical vapor deposition grown graphene heat spreader for thermal management of hot spots. Carbon, 2013, 61, 342-348. | 10.3 | 96 |
| 98 | Carbon nanotubes for electronics manufacturing and packaging: from growth to integration. Advances in Manufacturing, 2013, 1, 13-27. | 6.1 | 22 |
| 99 | Effect of substrates and underlayer on CNT synthesis by plasma enhanced CVD. Advances in Manufacturing, 2013, 1, 236-240. | 6.1 | 2 |
| 100 | Bioactive 3D cell culture system minimizes cellular stress and maintains the <i>in vivo</i> -like morphological complexity of astroglial cells. Glia, 2013, 61, 432-440. | 4.9 | 100 |
| 101 | Paper-mediated controlled densification and low temperature transfer of carbon nanotube forests for electronic interconnect application. Microelectronic Engineering, 2013, 103, 177-180. | 2.4 | 30 |
| 102 | Experimental study on electrical properties and stability of CNT bumps in high density interconnects. , 2013, , . | | 1 |
| 103 | Characterization of CNT Enhanced Conductive Adhesives in Terms of Thermal Conductivity. ECS Transactions, 2012, 44, 1011-1017. | 0.5 | 2 |
| 104 | Carbon Nanotubes in Electronics Interconnect Applications with a Focus on 3D-TSV Technology. ECS Transactions, 2012, 44, 683-692. | 0.5 | 5 |
| 105 | Direct Chemical Vapor Deposition of Large-Area Carbon Thin Films on Gallium Nitride for Transparent Electrodes: A First Attempt. IEEE Transactions on Semiconductor Manufacturing, 2012, 25, 494-501. | 1.7 | 23 |
| 106 | Through-Silicon Vias Filled With Densified and Transferred Carbon Nanotube Forests. IEEE Electron Device Letters, 2012, 33, 420-422. | 3.9 | 67 |
| 107 | Organic Thin-Film Transistors with Anodized Gate Dielectric Patterned by Self-Aligned Embossing on Flexible Substrates. Advanced Functional Materials, 2012, 22, 1209-1214. | 14.9 | 24 |
| 108 | Polymer-metal nanofibrous composite for thermal management of microsystems. Materials Letters, 2012, 75, 229-232. | 2.6 | 25 |

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| 109 | Surface characterisation of oxygen plasma treated electrospun polyurethane fibres and their interaction with red blood cells. <i>European Polymer Journal</i> , 2012, 48, 472-482. | 5.4 | 47 |
| 110 | Selective growth of double-walled carbon nanotubes on gold films. <i>Materials Letters</i> , 2012, 72, 78-80. | 2.6 | 19 |
| 111 | Thick film patterning by lift-off process using double-coated single photoresists. <i>Materials Letters</i> , 2012, 76, 117-119. | 2.6 | 9 |
| 112 | Formation of three-dimensional carbon nanotube structures by controllable vapor densification. <i>Materials Letters</i> , 2012, 78, 184-187. | 2.6 | 17 |
| 113 | Templated Growth of Covalently Bonded Three-Dimensional Carbon Nanotube Networks Originated from Graphene. <i>Advanced Materials</i> , 2012, 24, 1576-1581. | 21.0 | 37 |
| 114 | Molecular Gun Composed of Carbon Nanotube. <i>Journal of Computational and Theoretical Nanoscience</i> , 2011, 8, 1716-1719. | 0.4 | 3 |
| 115 | Study on the bimodal filler influence on the effective thermal conductivity of thermal conductive adhesive. <i>Microsystem Technologies</i> , 2011, 17, 93-99. | 2.0 | 1 |
| 116 | Carbon-Nanotube Through-Silicon Via Interconnects for Three-Dimensional Integration. <i>Small</i> , 2011, 7, 2313-2317. | 10.0 | 69 |
| 117 | Surface-Confined Synthesis of Silver Nanoparticle Composite Coating on Electrospun Polyimide Nanofibers. <i>Small</i> , 2011, 7, 3057-3066. | 10.0 | 43 |
| 118 | A Highly Conductive Bimodal Isotropic Conductive Adhesive and Its Reliability. <i>ECS Transactions</i> , 2011, 34, 583-588. | 0.5 | 12 |
| 119 | Study on the Reliability of Nano-Structured Polymer-Metal Composite for Thermal Interface Material. <i>ECS Transactions</i> , 2011, 34, 991-995. | 0.5 | 2 |
| 120 | The Effect of Functionalized Silver on Rheological and Electrical Properties of Conductive Adhesives. <i>ECS Transactions</i> , 2011, 34, 811-816. | 0.5 | 12 |
| 121 | Study on the Reliability of Fast Curing Isotropic Conductive Adhesive. <i>ECS Transactions</i> , 2011, 34, 805-810. | 0.5 | 8 |
| 122 | Design of Printed Monopole Antennas on Liquid Crystal Polymer Substrates. <i>Journal of Infrared, Millimeter, and Terahertz Waves</i> , 2010, 31, 469. | 2.2 | 1 |
| 123 | Modeling of the effective thermal conductivity of composite materials with FEM based on resistor networks approach. <i>Microsystem Technologies</i> , 2010, 16, 633-639. | 2.0 | 23 |
| 124 | Ultrafast Transfer of Metal-Enhanced Carbon Nanotubes at Low Temperature for Large-Scale Electronics Assembly. <i>Advanced Materials</i> , 2010, 22, 5039-5042. | 21.0 | 48 |
| 125 | Dry densification of carbon nanotube bundles. <i>Carbon</i> , 2010, 48, 3795-3801. | 10.3 | 39 |
| 126 | Flip Chip Assembly Using Carbon Nanotube Bumps and Anisotropic Conductive Adhesive Film. <i>ECS Transactions</i> , 2010, 27, 825-830. | 0.5 | 0 |

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| 127 | Direct Photolithographic Patterning of Electrospun Films for Defined Nanofibrillar Microarchitectures. <i>Langmuir</i> , 2010, 26, 2235-2239. | 3.5 | 52 |
| 128 | Computational fluid dynamics for effects of coolants on on-chip cooling capability with carbon nanotube micro-fin architectures. <i>Microsystem Technologies</i> , 2009, 15, 375-381. | 2.0 | 6 |
| 129 | Design of 50-70GHz Planar Wideband Bandpass Filter on Liquid Crystal Polymer Substrate. <i>Journal of Infrared, Millimeter, and Terahertz Waves</i> , 2009, 30, 183-189. | 2.2 | 1 |
| 130 | Nanoparticles of the Lead-free Solder Alloy Sn-3.0Ag-0.5Cu with Large Melting Temperature Depression. <i>Journal of Electronic Materials</i> , 2009, 38, 351-355. | 2.2 | 47 |
| 131 | Nanoparticles of SnAgCu lead-free solder alloy with an equivalent melting temperature of SnPb solder alloy. <i>Journal of Alloys and Compounds</i> , 2009, 484, 777-781. | 5.5 | 71 |
| 132 | Through silicon vias filled with planarized carbon nanotube bundles. <i>Nanotechnology</i> , 2009, 20, 485203. | 2.6 | 54 |
| 133 | Millimeter-wave ultra-wideband bandpass filter based on liquid crystal polymer substrates for automotive radar systems. <i>Microwave and Optical Technology Letters</i> , 2008, 50, 2276-2280. | 1.4 | 3 |
| 134 | Tensile properties and microstructural characterization of Sn-0.7Cu-0.4Co bulk solder alloy for electronics applications. <i>Journal of Alloys and Compounds</i> , 2008, 457, 97-105. | 5.5 | 55 |
| 135 | Effect of encapsulation on OLED characteristics with anisotropic conductive adhesive. , 2008, , . | | 0 |
| 136 | Experimental Investigation and Micropolar Modelling of the Anisotropic Conductive Adhesive Flip-Chip Interconnection. <i>Journal of Adhesion Science and Technology</i> , 2008, 22, 1717-1731. | 2.6 | 3 |
| 137 | Study of interfacial reactions in Sn-3.5Ag-3.0Bi and Sn-8.0Zn-3.0Bi sandwich structure solder joint with Ni(P)/Cu metallization on Cu substrate. <i>Journal of Alloys and Compounds</i> , 2007, 437, 169-179. | 5.5 | 30 |
| 138 | High temperature aging study of intermetallic compound formation of Sn-3.5Ag and Sn-4.0Ag-0.5Cu solders on electroless Ni(P) metallization. <i>Journal of Alloys and Compounds</i> , 2006, 425, 191-199. | 5.5 | 42 |
| 139 | Coffin-Manson constant determination for a Sn-8Zn-3Bi lead-free solder joint. <i>Soldering and Surface Mount Technology</i> , 2006, 18, 4-11. | 1.5 | 10 |
| 140 | Significance of intermediate production processes in life cycle assessment of electronic products assessed using a generic compact model. <i>Journal of Cleaner Production</i> , 2005, 13, 1269-1279. | 9.3 | 22 |
| 141 | Formulation and characterization of anisotropic conductive adhesive paste for microelectronics packaging applications. <i>Journal of Electronic Materials</i> , 2005, 34, 1420-1427. | 2.2 | 12 |
| 142 | A general Weibull model for reliability analysis under different failure Criteria-application on anisotropic conductive adhesive joining technology. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , 2005, 28, 322-327. | 1.4 | 6 |
| 143 | Integrated Capacitors and Resistors on Liquid Crystal Polymer Substrate. , 2005, , . | | 2 |
| 144 | Ontology for the anisotropic conductive adhesive interconnect technology for electronics packaging applications. , 2005, , . | | 3 |

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| 145 | LCA of electronic products. International Journal of Life Cycle Assessment, 2004, 9, 45-52. | 4.7 | 14 |
| 146 | Study on thermomechanical reliability of a tunable light modulator. Microelectronics Reliability, 2004, 44, 779-785. | 1.7 | 0 |
| 147 | Thermodynamic assessment of the Sn-Co lead-free solder system. Journal of Electronic Materials, 2004, 33, 935-939. | 2.2 | 43 |
| 148 | Theoretical Analysis of RF Performance of Anisotropic Conductive Adhesive Flip-Chip Joints. IEEE Transactions on Components and Packaging Technologies, 2004, 27, 546-550. | 1.3 | 18 |
| 149 | System-on-package: a broad perspective from system design to technology development. Microelectronics Reliability, 2003, 43, 1339-1348. | 1.7 | 9 |
| 150 | Comparison of isothermal mechanical fatigue properties of lead free solder joints and bulk solders. , 2003, , . | | 2 |
| 151 | Microwave-transmission, heat and temperature properties of electrically conductive adhesive. IEEE Transactions on Components and Packaging Technologies, 2003, 26, 193-198. | 1.3 | 14 |
| 152 | Electrical Conductive Characteristics of Anisotropic Conductive Adhesive Particles. Journal of Electronic Packaging, Transactions of the ASME, 2003, 125, 609-616. | 1.8 | 29 |
| 153 | Foreword - Fifth international IEEE symposium on high density packaging and component failure analysis (HDP'02). IEEE Transactions on Electronics Packaging Manufacturing, 2002, 25, 251-252. | 1.4 | 0 |
| 154 | Process development and adhesion behavior of electroless copper on liquid crystal polymer (LCP) for electronic packaging application. IEEE Transactions on Electronics Packaging Manufacturing, 2002, 25, 273-278. | 1.4 | 29 |
| 155 | Electrical characterization of isotropic conductive adhesive under mechanical loading. Journal of Electronic Materials, 2002, 31, 916-920. | 2.2 | 18 |
| 156 | LIFE CYCLE ASSESSMENT OF A TELECOMMUNICATIONS EXCHANGE. Journal of Electronics Manufacturing, 2000, 10, 147-160. | 0.4 | 13 |
| 157 | Experimental and theoretical characterization of electrical contact in anisotropically conductive adhesive. IEEE Transactions on Advanced Packaging, 2000, 23, 15-21. | 1.6 | 33 |
| 158 | A REVIEW OF MICROWAVE CURING OF POLYMERIC MATERIALS. Journal of Electronics Manufacturing, 2000, 10, 181-189. | 0.4 | 29 |
| 159 | Effect of Ag particle size on electrical conductivity of isotropically conductive adhesives. IEEE Transactions on Electronics Packaging Manufacturing, 1999, 22, 299-302. | 1.4 | 157 |
| 160 | Implementation of the Internet course on conductive adhesives for electronics packaging. , 0, , . | | 1 |
| 161 | Process development and reliability for system-in-a-package using liquid crystal polymer substrate. , 0, , . | | 8 |
| 162 | Effect of different temperature cycle profiles on the crack propagation and microstructural evolution of lead free solder joints of different electronic components. , 0, , . | | 15 |

| # | ARTICLE | IF | CITATIONS |
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| 163 | Reliability investigations for encapsulated isotropic conductive adhesives flip chip interconnection. , 0, , . | | 1 |